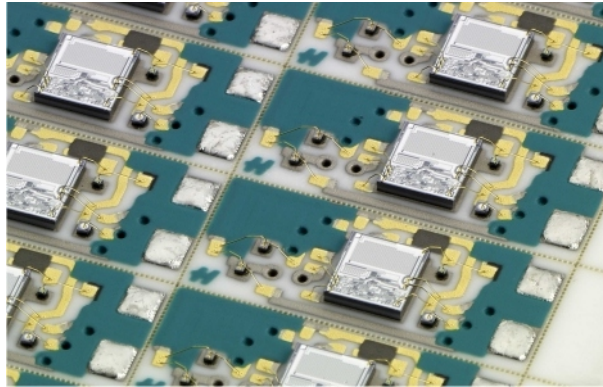


TECHNOLOGY

CHIPS SIZE:	SIDE 0.2 - 10mm THICKNESS 50 μ m	SUBSTRATES:	THICK FILM CERAMIC FR4, Fr5, G10, G11, ROGERS FLEX, RIGID FLEX, IMS PYREX ...
TRACEABILITY:	WAFER MAPPING	ADHESIVES:	CONDUCTIVE NON-CONDUCTIVE SILICONE
POSITIONING ACCURACY:	STANDARD +/- 30 μ m SPECIFIC +/- 15 μ m	ADHESIVE APPLICATION:	STAMPING DISPENSING SILK SCREEN PRINTING
PACKAGING:	WAFER UP TO 8" WAFFLE PACK 2 - 4" GELPACK		



HYBRID SA IS ABLE TO BOND CHIPS OF DIFFERENT SIZE AND THICKNESS ON DIFFERENT TYPES OF SUBSTRATES. POSITIONING ACCURACY AND OTHER PRODUCT SPECIFICATIONS ARE DETERMINED IN COLLABORATION WITH THE CLIENT.

